

# **Technical** Data Sheet

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# Chemask® NA High Temperature Solder Masking Agent

#### Product# CNA8, CNA1

#### **Product Description**

Chemask NA Non-Ammoniated Solder Masking Agent is a fast curing, peelable temporary spot mask formulated for safe use on sensitive metals. It contains high-temperature resistant compounds that protect component-free areas during wave soldering. Chemask NA may be used to protect pins, posts, contacts and edge connections in the solder reflow oven or during conformal coating processes.

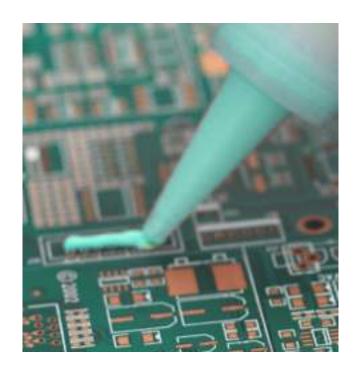
- Stable to 550°F (288°C)
- For lead-free or tin/lead processes
- Phthalate-free, low toxicity and environmentally safe
- Compatible with rosin, water soluble fluxes and cleaning solvents
- Dries tack free in 15 minutes
- Goes straight into the pre-heat oven
- · Removes easily and leaves no residue
- Non-contaminating, non-staining and non-corrosive
- Compatible with gold, copper, nickel, silver and OSP finishes
- RoHS compliant

#### **Typical Applications**

Chemask NA protects:

- · Component-free areas during wave and reflow soldering
- Components and pin connectors
- Temperature sensitive components during wave or reflow soldering





## **Typical Product Data and Physical Properties**

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Synthetic Resin
Green
Odorless
All types
Wave Soldering & Reflow
Lead Free & Tin/Lead
550°F/ 288°C
15 min.
30 min.
20,000 cps
DI water
Nonflammable
8.5 lbs.
2 years
Yes

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# Chemask® NA High Temperature Solder Masking Agent

### Product# CNA8, CNA1

#### Compatibility

Chemask NA is generally compatible with most materials used in printed circuit board fabrication. As with any solder masking agent, compatibility with substrate should be determined on a non-critical area prior to use.

### **Application Method**

Squeeze Bottle/Syringe	Yes
Spatula	Yes
Screening	Yes
Automatic Dispensing	Yes
Removal	By hand
Clean-up before curing	Use water

#### Usage Instructions

#### For industrial use only. Read SDS carefully prior to use.

Chemask NA solder masking agent is engineered for all electronic manufacturing applications. When applying by hand using squeeze bottle or spatula, insure that all areas of the pretinned hole are evenly covered on the side to be soldered. Automatic dispensing equipment may also be used as appropriate. Chemask NA may also be screen printed. Depending on ambient conditions, temporary mask may remain on assemblies for extended periods of time prior to processing.

**REMOVAL:** After allowing the Chemask NA to fully cure, the temporary mask can be removed by hand or using tweezers.

#### Availability

CM8 8 fl. oz. / 236 mL Liquid Squeeze Bottle

**CM1** 1 gal. / 3.7 L Liquid

#### **Environmental Impact Data**

CFC	0.0%
HCFC	0.0%
GWP	0.0%
VOC	0.0%
HFC	0.0%
ODP	0.00

CFC, HCFC, VOC, and HFC numbers shown are the content by weight. Ozone depletion potential (ODP) is determined in accordance with the Montreal Protocol and U.S. Clean Air Act of 1990. The ODP of this product is 0.0. It is the sum of the ODP of the substances that may contribute to the depletion of stratospheric ozone, based upon the weight of each substance in the product's formulation. Global warming potential (GWP) is calculated based on a 100 year time horizon. Carbon dioxide has a GWP of 1.

#### **Technical and Application Assistance**

Chemtronics provides a technical hotline to answer your technical and application related questions.

The toll free number is: 1-800-TECH-401.

#### Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

